

Product Change Notification - RMES-23QALB394

Date:

17 Apr 2019

Product Category:

Ethernet PHYs

Affected CPNs:

Notification subject:

CCB 3306 and 3306.001 Final Notice: Qualification of ASE as a new assembly site for selected Micrel products available in 32L (5x5x0.9mm) and 24L (4x4x0.9mm) VQFN package.

Notification text:
PCN Status:

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of ASE as a new assembly site for selected Micrel products available in 32L (5x5x0.9mm) and 24L (4x4x0.9mm) VQFN package.

Pre Change:

Assembled at TICIP assembly site using CEL-9200 mold compound material and NiPdAu lead plating.

Post Change:

Assembled at ASE assembly site using EME-G631H mold compound material and Matte tin finish plating

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	Taiwan IC Packing Corp. (TICP)	ASE Inc. (ASE)
Wire material	Au	Au
Die attach material	EN4900	EN4900
Molding compound material	CEL-9220	EME-G631H
Lead frame material	C194	C194
Lead Plating	NiPdAu	Matte Tin Finish

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability and on-time delivery performance by qualifying ASE as new assembly site.



Change Implementation Status:

In progress

Estimated First Ship Date:

May 17, 2019 (date code: 1920)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	August 2018						April 2019					May 2019			
Workweek	31	32	33	34	35		14	15	16	17	18	19	20	21	22
Initial PCN Issue Date				X											
Qualification Report Availability									X						
Final PCN Issue Date									X						
Estimated Implementation Date													X		

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:

August 24, 2018: Issued initial notification.

April 17, 2019: Issued final notification. Attached the qualification report. Corrected the lead frame material from C7025 to C194 in Pre and Post Change Summary table. Added reference CCB 3306.001 and updated notification subject and description of change because of the update in the scope of this PCN to add 24L (4x4x0.9mm) VQFN package.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_RMES-23QALB394_Qual_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

KSZ8051MNLU
KSZ8051MNLU-TR
KSZ8051MNLV
KSZ8051MNLV-TR
KSZ8051RNLUB-TR-VAO
KSZ8051RNLUB-VAO
KSZ8051RNLU-TR
KSZ8081RNAIA-G3XX-TR
KSZ8081RNDCA-G3XX
KSZ8081RNDCA-G3XX-TR
KSZ8091RNAIA-G3XX-TR
SPNY801142-TR
SPNY801143-TR
SPNY801147-TR
SPNY801148-TR
SPNZ801128-TR
SPNZ801142-TR
SPNZ801143
SPNZ801143-TR